# 2.5V/3.3V, 14GHz ÷2 Clock Divider w/CML Output and Internal Termination

# Description

The NB7L32M is an integrated ÷2 divider with differential clock inputs and asynchronous reset.

Differential clock inputs incorporate internal 50  $\Omega$  termination resistors and accept LVPECL (Positive ECL), CML, or LVDS. The high frequency reset pin is asserted on the rising edge. Upon power–up, the internal flip–flops will attain a random state; the reset allows for the synchronization of multiple NB7L32M's in a system.

The differential 16 mA CML output provides matching internal 50  $\Omega$  termination which guarantees 400 mV output swing when externally receiver terminated 50  $\Omega$  to  $V_{CC}$  (See Figure 15).

The device is housed in a small 3x3 mm 16 pin QFN package.

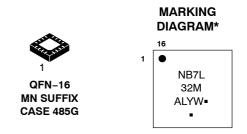
### **Features**

- Maximum Input Clock Frequency 14 GHz Typical
- 200 ps Max Propagation Delay
- 30 ps Typical Rise and Fall Times
- < 0.5 ps Maximum (RMS) Random Clock Jitter
- Operating Range:  $V_{CC} = 2.375 \text{ V}$  to 3.465 V with  $V_{EE} = 0 \text{ V}$
- CML Output Level (400 mV Peak-to-Peak Output), Differential Output Only
- 50  $\Omega$  Internal Input and Output Termination Resistors
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- These are Pb-Free Devices



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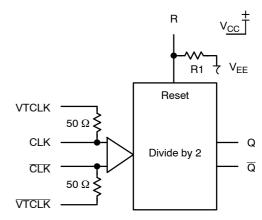
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A = Assembly Location

L = Wafer Lot
Y = Year
W = Work Week
= Pb-Free Package

### **FUNCTIONAL BLOCK DIAGRAM**



# **TRUTH TABLE**

| CLK | CLK | R | Q  | Q  |
|-----|-----|---|----|----|
| х   | х   | Н | L  | Н  |
| Z   | W   | L | ÷2 | ÷2 |

Z = LOW to HIGH Transition W = HIGH to LOW Transition x = Don't Care

## **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

<sup>\*</sup>For additional marking information, refer to Application Note AND8002/D.

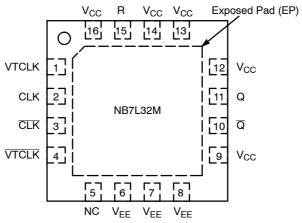


Figure 1. Pin Configuration (Top View)

# **Table 1. PIN DESCRIPTION**

| Pin                  | Name            | I/O                  | Description   |  |
|----------------------|-----------------|----------------------|---|--|
| 1                    | VTCLK           | -                    | Internal 50 $\Omega$ termination pin. In the differential configuration when the input termination pin (VTCLK, VTCLK) are connected to a common termination voltage or left open, and if no signal is applied on CLK/CLK input then the device will be susceptible to self–oscillation. |  |
| 2                    | CLK             | ECL, CML, LVDS Input | Noninverted differential input. In the differential configuration when the input termination pin (VTCLK, VTCLK) are connected to a common termination voltage or left open and if no signal is applied on CLK/CLK input, then the device will be susceptible to self-oscillation.       |  |
| 3                    | CLK             | ECL, CML, LVDS Input | Inverted differential input. In the differential configuration when the input termination pin (VTCLK, VTCLK) are connected to a common termination voltage or left open and if no signal is applied on CLK/CLK input, then the device will be susceptible to self-oscillation.          |  |
| 4                    | VTCLK           | -                    | Internal 50 $\Omega$ termination pin. In the differential configuration when the input termination pin (VTCLK, VTCLK) are connected to a common termination voltage or left open and if no signal is applied on CLK/CLK input, then the device will be susceptible to self–oscillation. |  |
| 5                    | NC              | -                    | No connect. NC pin must be left open.   |  |
| 6, 7, 8              | $V_{EE}$        | -                    | Negative supply voltage.  |  |
| 9, 12, 13,<br>14, 16 | V <sub>CC</sub> | -                    | Positive supply voltage.  |  |
| 10                   | Q               | CML Output           | Inverted differential output. Typically terminated with 50 $\Omega$ resistor to V $_{CC}$ .   |  |
| 11                   | Q               | CML Output           | Noninverted differential output. Typically terminated with 50 $\Omega$ resistor to $V_{CC}$ .   |  |
| 15                   | R               | LVTTL/LVCMOS         | Reset Input. Internal pulldown to 75 k $\Omega$ to $V_{EE}$ .   |  |
| _                    | EP              | -                    | Exposed Pad. The thermally exposed pad (EP) on package bottom (see case drawing) must be attached to a heat–sinking conduit. EP is electrically isolated from $V_{CC}$ and $V_{EE}$ .   |  |

**Table 2. ATTRIBUTES** 

| Characterist   | Value                             |                      |  |  |  |
|--|-----------------------------------|----------------------|--|--|--|
| Internal Input Pulldown Resistor                       | R1                                | 75 kΩ                |  |  |  |
| ESD Protection   | Human Body Model<br>Machine Model | > 500 V<br>> 30 V    |  |  |  |
| Moisture Sensitivity (Note 1)                          | QFN-16                            | Level 1              |  |  |  |
| Flammability Rating                                    | Oxygen Index: 28 to 34            | UL 94 V-0 @ 0.125 in |  |  |  |
| Transistor Count                                       | 349                               |                      |  |  |  |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test |                                   |                      |  |  |  |

<sup>1.</sup> For additional information, see Application Note AND8003/D.

**Table 3. MAXIMUM RATINGS** 

| Symbol            | Parameter  | Condition 1                                    | Condition 2   | Rating       | Unit         |
|-------------------|--|--|---|--------------|--------------|
| V <sub>CC</sub>   | Positive Power Supply                              | V <sub>EE</sub> = 0 V                          |   | 3.6          | V            |
| V <sub>EE</sub>   | Negative Power Supply                              | V <sub>CC</sub> = 0 V                          |   | -3.6         | V            |
| VI                | Positive Input<br>Negative Input                   | V <sub>EE</sub> = 0 V<br>V <sub>CC</sub> = 0 V | $\begin{array}{c} V_I \leq V_{CC} \\ V_I \geq V_{EE} \end{array}$ | 3.6<br>-3.6  | V            |
| V <sub>INPP</sub> | Differential Input Voltage                         |  |   | 2.8          | V            |
| I <sub>IN</sub>   | Input Current Through $R_T$ (50 $\Omega$ Resistor) | Static<br>Surge                                |   | 45<br>80     | mA<br>mA     |
| l <sub>out</sub>  | Output Current                                     | Continuous<br>Surge                            |   | 25<br>50     | mA<br>mA     |
| T <sub>A</sub>    | Operating Temperature Range                        | QFN-16   |   | -40 to +85   | °C           |
| T <sub>stg</sub>  | Storage Temperature Range                          |  |   | -65 to +150  | °C           |
| $\theta_{\sf JA}$ | Thermal Resistance (Junction-to-Ambient) (Note 2)  | 0 lfpm<br>500 lfpm                             | QFN-16<br>QFN-16  | 41.6<br>35.2 | °C/W<br>°C/W |
| $\theta_{\sf JC}$ | Thermal Resistance (Junction-to-Case)              | 1S2P   | QFN-16  | 4.0          | °C/W         |
| T <sub>sol</sub>  | Wave Solder Pb-Free                                | <3 sec @ 260°C                                 |   | 265          | °C           |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

<sup>2.</sup> JEDEC standard multilayer board – 1S2P (1 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 4. DC CHARACTERISTICS, CLOCK INPUTS, CML OUTPUTS  $V_{CC}$  = 2.375 V to 3.465 V,  $V_{EE}$  = 0 V,  $T_A = -40^{\circ}C \text{ to } +85^{\circ}C$ 

| Symbol                    |                                 | Characteristic                         |         | Min                   | Тур                   | Max                   | Unit  |
|---------------------------|---------------------------------|--|---------|-----------------------|-----------------------|-----------------------|-------|
| I <sub>CC</sub>           | Power Supply Current (Not       | e 3)                                   |         | 50                    | 65                    | 80                    | mA    |
| V <sub>OH</sub>           | Output HIGH Voltage (Note       | 4)                                     |         | V <sub>CC</sub> – 40  | V <sub>CC</sub> – 10  | V <sub>CC</sub>       | mV    |
| V <sub>OL</sub>           | Output LOW Voltage (Note        | 4)                                     |         | V <sub>CC</sub> – 500 | V <sub>CC</sub> – 400 | V <sub>CC</sub> – 300 | mV    |
| R <sub>TOUT</sub>         | Internal Output Termination     | Resistor                               |         | 45                    | 50                    | 55                    | Ω     |
| R <sub>Temp</sub><br>Coef | Internal I/O Termination Re     | sistor Temperature Coefficient         |         |                       | 6.38                  |                       | mΩ/°C |
| DIFFERE                   | NTIAL CLK/CLK INPUT DR          | IVEN SINGLE-ENDED (see Figure 9 and    | 11)     |                       |                       |                       |       |
| $V_{th}$                  | Input Threshold Reference       | Voltage Range (Note 6)                 |         | 1050                  |                       | V <sub>CC</sub>       | mV    |
| V <sub>IH</sub>           | Single-ended Input HIGH         | /oltage                                |         | V <sub>th</sub> + 150 |                       | V <sub>CC</sub> + 300 | mV    |
| V <sub>IL</sub>           | Single-ended Input LOW V        | oltage                                 |         | V <sub>EE</sub>       |                       | V <sub>th</sub> – 150 | mV    |
| DIFFERE                   | NTIAL CLK/CLK INPUTS D          | RIVEN DIFFERENTIALLY (see Figure 10    | and 12) |                       |                       |                       |       |
| $V_{IHD}$                 | Differential Input HIGH Volt    | age                                    |         | 1200                  |                       | V <sub>CC</sub> + 300 | mV    |
| $V_{ILD}$                 | Differential Input LOW Volta    | age                                    |         | $V_{EE}$              |                       | V <sub>CC</sub> – 75  | mV    |
| V <sub>CMR</sub>          | Input Common Mode Rang          | e (Differential Configuration, Note 7) |         | 1125                  |                       | V <sub>CC</sub>       | mV    |
| $V_{\text{ID}}$           | Differential Input Voltage (V   | I <sub>IHD</sub> – V <sub>ILD</sub> )  |         | 150                   |                       | 2500                  | mV    |
|                           |                                 |  |         |                       |                       | •                     | •     |
| I <sub>IH</sub>           | Input HIGH Current              | CLK/CLK (VTCLK/R/VTCLK/R Oper          | n)      | 0                     | 30                    | 100                   | μΑ    |
| I <sub>IL</sub>           | Input LOW Current               | CLK/CLK(VTCLK/R/VTCLK/R Oper           | n)      | -50                   | 0                     | 50                    | μΑ    |
| R <sub>TIN</sub>          | Internal Input Termination F    | Resistor                               |         | 45                    | 50                    | 55                    | Ω     |
| LVTTL/L\                  | CMOS RESET INPUT                |  |         | •                     | •                     | •                     | 1     |
| V <sub>IH</sub>           | Single-ended Input HIGH Voltage |  |         | 2000                  |                       | V <sub>CC</sub>       | mV    |
| V <sub>IL</sub>           | Single-ended Input LOW V        | oltage                                 |         | V <sub>EE</sub>       |                       | 800                   | mV    |
| I <sub>IH</sub>           | Input HIGH Current              |  | R       | 0                     | 30                    | 100                   | μΑ    |
| I <sub>IL</sub>           | Input LOW Current               |  | R       | 0                     | 10                    | 100                   | μΑ    |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 3. Input termination pins open and all outputs loaded with external  $R_L$  = 50  $\Omega$  receiver termination resistor.
- 4. CML outputs require  $R_L = 50 \Omega$  receiver termination resistors to  $V_{CC}$  for proper operation. (See Figure 8) 5. Input and output parameters vary 1:1 with  $V_{CC}$ .
- 6. V<sub>th</sub> is applied to the complementary input when operating in single-ended mode.
- 7.  $V_{CMR(MIN)}$  varies 1:1 with  $V_{EE}$ ,  $V_{CMR}$  max varies 1:1 with  $V_{CC}$ . The  $V_{CMR}$  range is referenced to the most positive side of the differential input

Table 6. AC CHARACTERISTICS  $V_{CC} = 2.375 \text{ V}$  to 3.465 V,  $V_{EE} = 0 \text{ V}$  (Note 8)

|  |   |   |            | -40°C        | ;          |            | 25°C         |            |            | 85°C         |            |      |
|--|---|---|------------|--------------|------------|------------|--------------|------------|------------|--------------|------------|------|
| Symbol                                 | Characteristic  |   | Min        | Тур          | Max        | Min        | Тур          | Max        | Min        | Тур          | Max        | Unit |
| V <sub>OUTPP</sub>                     | Output Voltage Amplitude (@ V <sub>INPP</sub> (See Figures 2, 3, 4, 5, and 6) | $f_{in} \le 7 \text{ GHz}$<br>$f_{in} \le 12 \text{ GHz}$ | 190<br>160 | 330<br>320   |            | 190<br>160 | 330<br>320   |            | 190<br>160 | 330<br>320   |            | mV   |
| f <sub>IN</sub>                        | Maximum Input Clock Frequency (See Figure 2)                                  |   | 12         | 14           |            | 12         | 14           |            | 12         | 14           |            | GHz  |
| t <sub>PLH</sub> ,<br>t <sub>PHL</sub> | Propagation Delay to<br>Output Differential (See Figure 7)                    | CLK to Q<br>R to Q  | 130<br>200 | 155<br>240   | 200<br>300 | 130<br>200 | 155<br>240   | 200<br>300 | 130<br>200 | 155<br>260   | 200<br>300 | ps   |
| t <sub>skew</sub>                      | Duty Cycle Skew (Note 9)<br>Device-to-Device Skew (Note 12)                   |   |            | 2<br>6       | 20<br>50   |            | 2<br>6       | 20<br>50   |            | 2<br>6       | 20<br>50   |      |
| t <sub>RR</sub>                        | Reset Recovery (See Figure 7)   |   | 300        | 135          |            | 300        | 135          |            | 300        | 135          |            | ps   |
| t <sub>PW</sub>                        | Minimum Pulse Width   | R   | 500        | 210          |            | 500        | 210          |            | 500        | 210          |            | ps   |
| t <sub>JITTER</sub>                    | Random Clock Jitter (RMS)<br>(Note 11)  | f <sub>in</sub> ≤ 7 GHz<br>f <sub>in</sub> = 12 GHz       |            | 0.13<br>0.14 | 0.5<br>0.5 |            | 0.13<br>0.14 | 0.5<br>0.5 |            | 0.13<br>0.14 | 0.5<br>0.5 | ps   |
| V <sub>INPP</sub>                      | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 10)        | )   | 150        |              | 2500       | 150        |              | 2500       | 150        |              | 2500       | mV   |
| t <sub>r</sub><br>t <sub>f</sub>       | Output Rise/Fall Times @ 1 GHz (20% - 80%)                                    |   |            | 30           | 45         |            | 30           | 45         |            | 30           | 45         | ps   |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8. Measured by forcing  $V_{INPP(MIN)}$  from a 50% duty cycle clock source. All loading with an external  $R_L = 50 \Omega$  to  $V_{CC}$ . Input edge rates 40 ps (20% 80%).
- 9. Duty cycle skew is measured between differential outputs using the deviations of the sum of Tpw- and Tpw+ 1 GHz.
- $10. V_{INPP(MAX)} \ cannot \ exceed \ V_{CC} V_{EE}. \ Input \ voltage \ swing \ is \ a \ single-ended \ measurement \ operating \ in \ differential \ mode.$
- 11. Additive RMS jitter with 50% duty cycle input clock signal.
- 12. Device-to-device skew is measured between outputs under identical transition @ 1 GHz.

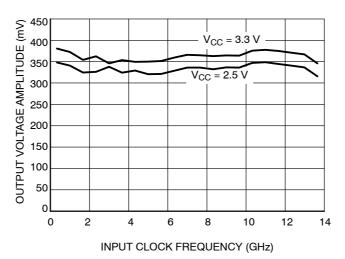


Figure 2. Output Voltage Amplitude ( $V_{OUTPP}$ ) versus Input Clock Frequency ( $f_{OUT}$ ) at Ambient Temperature ( $V_{INPP} = 150 \text{ mV}$ )

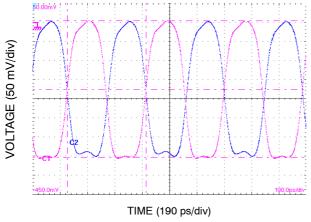


Figure 3. Typical Output Waveform with  $f_{IN}$  = 7 GHz(  $V_{CC}$  = 2.5 V,  $V_{INPP}$  = 400 mV, Room Temperature,  $V_{OUTPP}$  = 357 mV,  $t_r$  = 33 ps,  $t_f$  = 30 ps,  $t_{OUT}$  = 3.499 GHz)

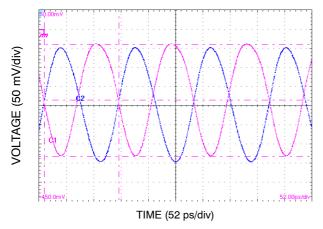


Figure 5. Typical Output Waveform with  $f_{IN}$  = 14 GHz( $V_{CC}$  = 2.5 V,  $V_{INPP}$  = 400 mV, Room Temperature,  $V_{OUTPP}$  = 292 mV,  $t_r$  = 25 ps,  $t_f$  = 27 ps,  $t_{OUT}$  = 7.01 GHz)

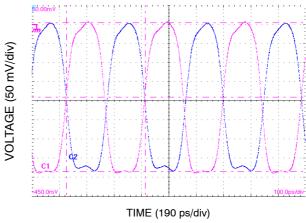


Figure 4. Typical Output Waveform with  $f_{IN} = 7 \text{ GHz}(V_{CC} = 3.3 \text{ V}, V_{INPP} = 400 \text{ mV}, Room Temperature, <math>V_{OUTPP} = 387 \text{ mV}, t_r = 32 \text{ ps}, t_f = 29.8 \text{ ps}, f_{OUT} = 3.499 \text{ GHz})$ 

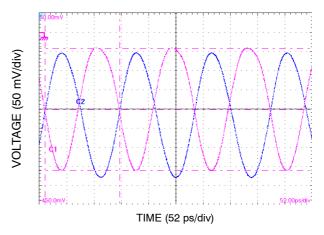


Figure 6. Typical Output Waveform with  $f_{IN} = 14 \text{ GHz}(V_{CC} = 3.3 \text{ V}, V_{INPP} = 400 \text{ mV}, \\ \text{Room Temperature}, V_{OUTPP} = 319 \text{ mV}, \\ \text{tr} = 25 \text{ ps}, t_f = 26 \text{ ps}, f_{OUT} = 7.01 \text{ GHz})$ 

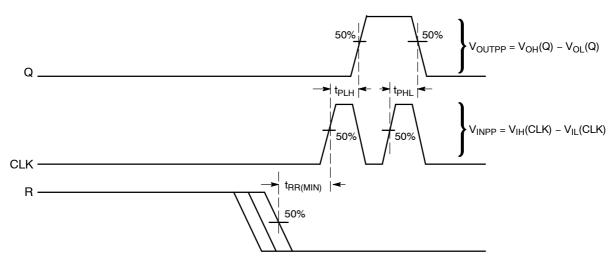


Figure 7. AC Reference Measurement (Timing Diagram)

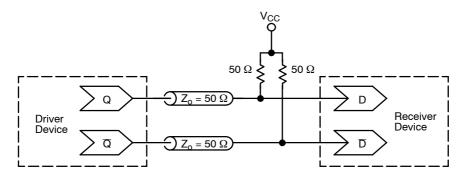
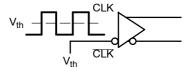


Figure 8. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8073/D – Termination of CML Logic Devices.)



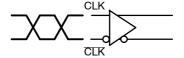


Figure 9. Differential Input Driven Single-Ended

Figure 10. Differential Inputs Driven Differentially

 $V_{\mathsf{IHDmax}}$ 

 $V_{IHDtyp}$ 

 $V_{\text{ILDtyp}}$ 

 $V_{IHDmin}$ 

 $V_{ILDmin}$ 

 $V_{ILDmax}$   $V_{ID} = V_{IHD} - V_{ILD}$ 

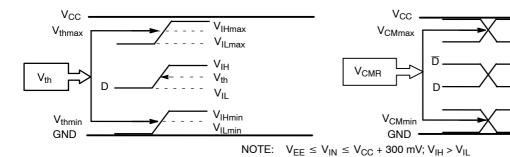


Figure 11. V<sub>th</sub> Diagram

Figure 12. V<sub>CMR</sub> Diagram

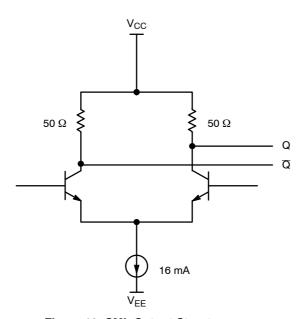


Figure 13. CML Output Structure

# **APPLICATION INFORMATION**

All NB7L32M inputs can accept PECL, CML, and LVDS signal levels. The limitations for differential input signal (LVDS, PECL, or CML) are minimum input swing of 150 mV and the maximum input swing of 2500 mV. Within these conditions, the input voltage can range from  $V_{CC}$  to 1.2 V. Examples interfaces are illustrated below in a 50  $\Omega$  environment (Z = 50  $\Omega$ ). For output termination and interface, refer to application note AND8020/D.

**Table 5. INTERFACING OPTIONS** 

| Interfacing Options | Connections  |  |  |
|---------------------|--|--|--|
| CML                 | Connect VTD and VTD to V <sub>CC</sub> (See Figure 14)                               |  |  |
| LVDS                | Connect VTD and VTD Together (See Figure 16)   |  |  |
| AC-COUPLED          | Bias VTD and VTD Inputs within Common Mode Range (V <sub>CMR</sub> ) (See Figure 15) |  |  |
| RSECL, PECL, NECL   | Standard ECL Termination Techniques (See Figure 8)                                   |  |  |

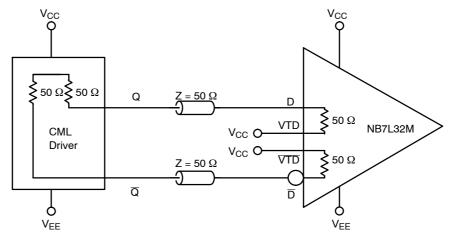
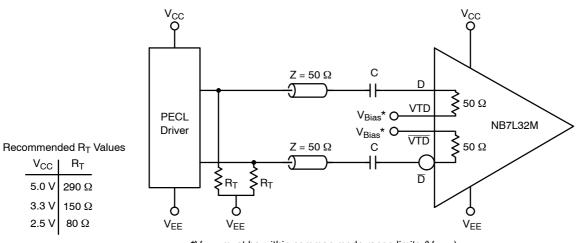


Figure 14. CML to NB7L32M Interface



 $^*\mbox{V}_{\mbox{\footnotesize Bias}}$  must be within common mode range limits (V\_{\mbox{\footnotesize CMR}})

Figure 15. PECL to NB7L32M Interface

# **APPLICATION INFORMATION**

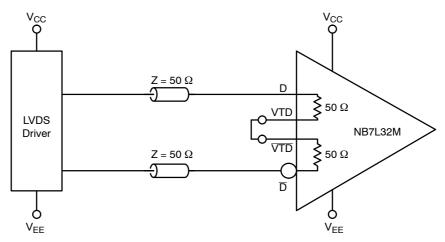


Figure 16. LVDS to NB7L32M Interface

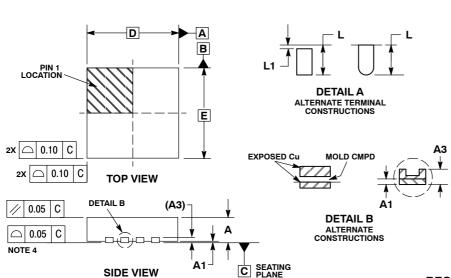
# **ORDERING INFORMATION**

| Device       | Package             | Shipping <sup>†</sup> |
|--------------|---------------------|-----------------------|
| NB7L32MMNG   | QFN-16<br>(Pb-Free) | 123 Units / Rail      |
| NB7L32MMNR2G | QFN-16<br>(Pb-Free) | 3000 / Tape & Reel    |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

### PACKAGE DIMENSIONS

# **QFN16 3x3, 0.5P** CASE 485G-01 ISSUE F



0.10 C A B

**E2** 

0.10 | C | A | B

0.05 C

NOTE 3

16X b

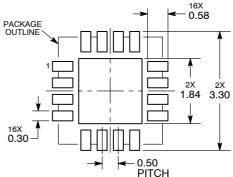
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### NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS. B. DIMENSION 6 APPLIES TO PLATED
- DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
- 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

|     | MILLIMETERS |           |      |  |  |  |  |
|-----|-------------|-----------|------|--|--|--|--|
| DIM | MIN         | MIN NOM I |      |  |  |  |  |
| Α   | 0.80        | 0.90      | 1.00 |  |  |  |  |
| A1  | 0.00        | 0.03      | 0.05 |  |  |  |  |
| А3  | C           | .20 REF   | :    |  |  |  |  |
| b   | 0.18        | 0.24      | 0.30 |  |  |  |  |
| D   | 3           | .00 BSC   | ;    |  |  |  |  |
| D2  | 1.65        | 1.75      | 1.85 |  |  |  |  |
| Е   | 3           | .00 BSC   | ;    |  |  |  |  |
| E2  | 1.65        | 1.75      | 1.85 |  |  |  |  |
| е   | 0           | 0.50 BSC  |      |  |  |  |  |
| K   | C           | 0.18 TYP  |      |  |  |  |  |
| Ĺ   | 0.30        | 0.40 0.50 |      |  |  |  |  |
| L1  | 0.00        | 0.08      | 0.15 |  |  |  |  |

# RECOMMENDED SOLDERING FOOTPRINT\*



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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